

BOARD'S DRILL SCHEDULE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Tolerance	COMMENT
0	.00795	80	YES		
	. 05	50	YES		
\square	.094488189	2	YES		
	. 12	2	YES		

Board Characteristics

0. Materials can be changed as required by application

- 1. All dimensions in mm, unless specified
- 2. Minimum trace width/gap: 5 mils

3. 0.5 Oz Copper on both layers, Dielectric thickness: max 2.5 mils 4. Silkscreen on Component Side.

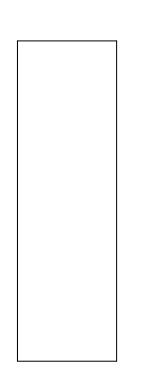
5. Polyimide Coverlay (Kapton Soldermask) on Top and Bottom, as per Gerbers

6. Soft Au finish (ENIG) for Al wire bonding and hand soldering on all pads.

7. Place Stiffener on Top (Component) side of Flex PCB.

8. Stiffener size as per flex PCB





Stiffener 1mmThick

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES		CONTRACT NO.			UNIVERSITY OF CHICA Electronics development						
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Ţ	TREATMENT		DRAWN M. Bogdan		10/6/2021			Specificat			ion Dra
F	FINISH		CHECKED	M.Bogdan	10/6/2021	S I 7 F	FSCM N(I			
		I S S U E D							3007 - B		
S	MILAR TO AC	T.WT CALC WT				SCALE	1 /	1		•	SHEET

Film 2 - Bottom

Film 1 - Component Side

Layer Order 2-Layer Flex PCB

